

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Su-Dong SHIN	04/23/2010
Myoung-Jin KIM	04/23/2010
Jeong-Hun HEO	04/23/2010
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd.
Street Address:	416 Maetan-dong, Yeongtong-gu,
Internal Address:	Gyeonggi-do,
City:	Suwon-si
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12836985
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OP \$40.00 12836985

Total Attachments: 2
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PATENT
REEL: 024711 FRAME: 0508

ASSIGNMENT

WHEREAS We, **SHIN, Su-Dong** of #5-304 Moran Apt., Ssangyong-dong, Seobuk-gu, Cheonan-si, Chungcheongnam-do, Republic of Korea, **KIM, Myoung-Jin** of #204-1204 Hyundai Hometown I-Park Apt., 2041 Ssangyong-dong, Seobuk-gu, Cheonan-si, Chungcheongnam-do, Republic of Korea, and **HEO, Jeong-Hun** of #303-901 Tangeong Samsung Trapalace, Myeong-am-ri, Tangeong-myeon, Asan-si, Chungcheongnam-do, Republic of Korea, a (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

HORIZONTAL INJECTION MOLD SYSTEM AND INJECTION MOLDING METHOD USING THE SAME

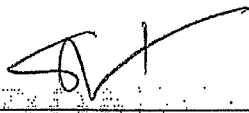
which claims priority to **Korea Application No. 10-2009-0128221**, filed on December 21, 2009, and for which We are about to file or have filed an application for Letters Patent of the United States;

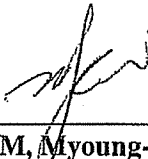
AND WHEREAS, **Samsung Electronics Co., Ltd.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of **Korea** having a place of business at **416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

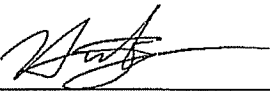
NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that

the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 2010. 4. 23  _____ L.S.
SHIN, Su-Dong

Date: 2010. 4. 23  _____ L.S.
KIM, Myoung-Jin

Date: 2010. 4. 23  _____ L.S.
HEO, Jeong-Hun